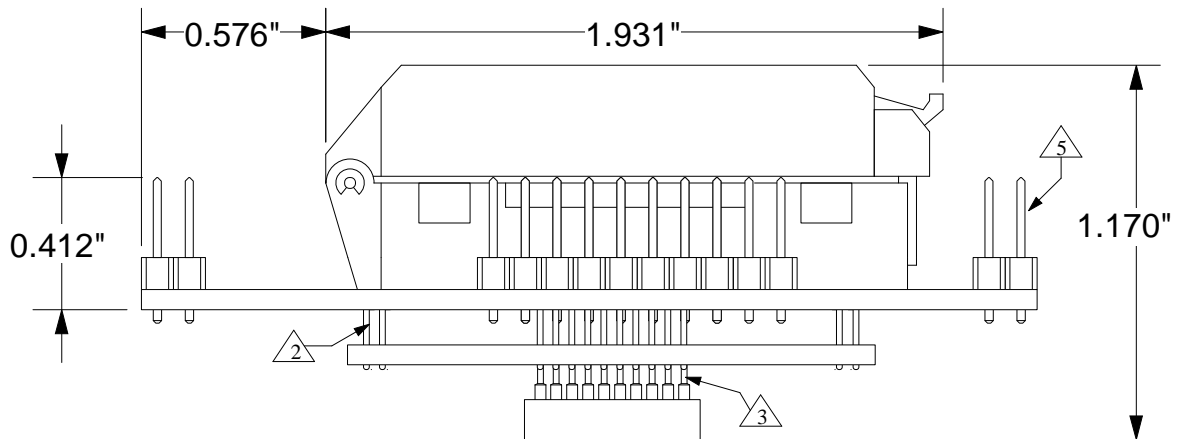


Top View




Side View

- 1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- 2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- 3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)
- 5 Test points: material- Phosphor Bronze; plating- Sn over 50µ" Ni. Gold flash on contact end.

Description: Carrier Adaptor

100 position (0.65mm pitch) QFP Zero Insertion Force socket with test points to 100 position Mini-grid socket interface.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

CA-QFE100RE-M-Z-T-01 Drawing		Status: Released	Scale 3:2	Rev: B
 <p>© 1996 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: P. Ilavarasan		Date: 9/3/96	
	File:CA-QFE100RE-M-Z-T-01 Dwg		Modified: 8/17/98	